

Status of ASIC board development for Barrel EMC

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Barrel EMC



Construction summary:

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- Barrel EMC consists of 11360 crystals
- Each crystal equipped with two LAAPDs {better light collection}
- Two LAAPDs are connected to one APFEL ASIC (hosts two independent preamplifiers)
- APFEL ASIC (two inputs) has high and low gain outputs (per each input) {high dynamic range}

ASIC integration challenges:

- ASIC power consumption
- Limited space

ASIC Integration Challenges

 To reduce ASIC power consumption APFEL has no low-ohmic line driver

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- The space restriction/density of the ASIC outputs forces to use Kapton flexible flat cable
- Kapton cable has large capacitance





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ASIC Integration Challenges



Solutions:

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- Reduce length of the Kapton cable and to put additional line driver close to ASIC – no space
- Build low-ohmic line driver into the ASIC – 10× increase of power consumption
- Use different types of the cable between ASIC and SADC – complicated connector in the cold area



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Ски To Be Investigated

- Performance of the current APFEL ASIC with reasonably long Kapton cable (~150 mm)
- Design of the additional line driver
- The effect of additional cable between the ASIC and line driver

ASIC board has to have flexible design





Separation of the line-driver board from ASIC board will allow:

- To investigate the effect of the connector
- To try different designs of the line-driver board (simple/smaller)
- Test effect of the additional cable between ASIC board and line driver







- The design of the capsule part and cable is ready
- The design of the Line-driver part is finished
- The design is adapted for prototype production; we are in contact with two companies:
 - Thales Nederland B.V. (www.thales-nederland.nl) can not produce the board (too challenging)
 - → GS-swiss PCB AG (www.swisspcb.ch) for prototype and mass production
- We expect to have boards produced in <u>October-</u> <u>November</u>

KVI (on behalf of Peter Wieczorek, GSI)

- The APFEL-III ASIC will be submitted for production in October-November
- Before submission we have to decide on the parameters of ASIC build-in line driver (optimize for the Kapton cable)
- Test setup of 4×4 crystals equipped with ASIC APFEL-II ASIC preamplifiers is being built at GSI (first measurements October). The Goals:
 - Investigate APFEL-II performance with cosmic rays/beams in the close to ideal environment (no Kapton cable)

KVI Feature Extraction Algorithms (VHDL implementation)



At present:

- All test measurements done with SADC (~10 μs long traces are stored for each event)
- Feature extraction algorithms implemented in software (C++ programs) and tested on collected data
- Feature extraction algorithm should analyse data on-line on digitizer module (FPGA)
- No prototype of PANDA Digitizer is available



Data-collection chain

VI Feature Extraction Algorithms (VHDL implementation)



PANDA SADC prototypes:

- PANDA SADC prototype (Pawel Marciniewski, Uppsala):
 - 16 channels, 14 bit, >100 MHz, optical link output
 - Available next year
- FEBEX 1/16 SADC developed at GSI (Jan Hoffman)
 - 16 channels, 12 bit, 67 MHz, optical link output
 - Board available in October

Using FPGA development board to analyse measured data:



VI Feature Extraction Algorithms (VHDL implementation)



- Analysis of measured data using FPGA test board almost ready
- "Porting" feature extraction algorithm to FEBEX 1/16 SADC board – beginning of 2010
- "Porting" for PANDA SADC prototype second part of 2010

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VI Feature Extraction Algorithms (VHDL implementation)



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Thank You for Your Attention!